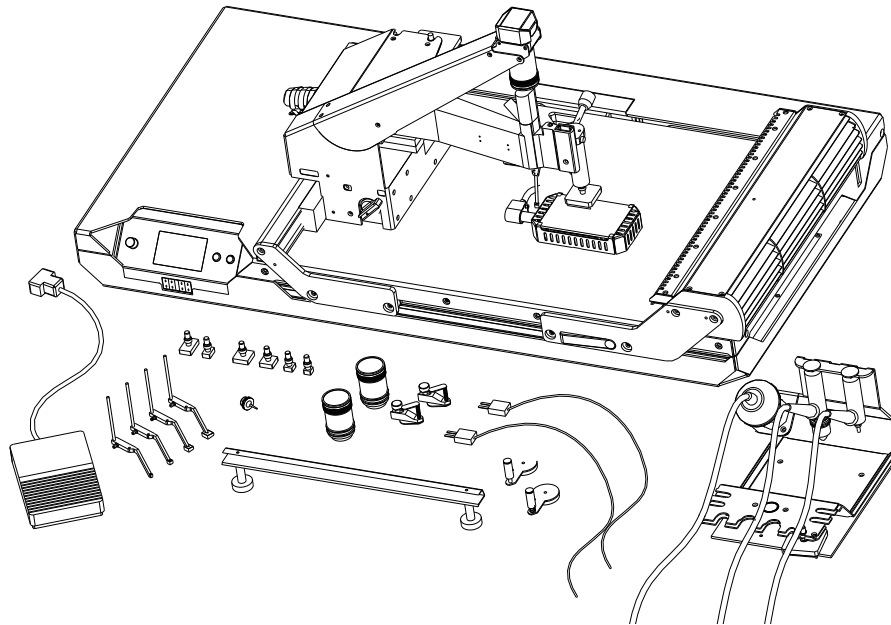


EXPERT 10.6 IV



Rework Station with 110W IR under heater (80x60mm²) and automated SMD placement process by Auto Vision Placer (AVP), incl. Easy Solder software package and DBL 06 control unit with six high resolution sensor inputs for thermocouples (Type K).

This system is particularly suitable for small PCBs which you can find in Smartphones and PDAs with Fin Pitch components in varying package dimensions.

Standard Equipment (Art.No. DB00.1068)

- Tool set for dispensing, placing, residual solder removal and soldering with magazine
- Set of placement nozzles (BGA/CSP) 3mm, 5mm, 8mm, 10mm
- Set of soldering nozzles (CSP/QFN), 9mm, 11mm 13mm, 16mm
- Set of soldering nozzles (SO) 10x15mm², 15x25mm²
- Placement nozzle for manual placement of small components (0,5mm)
- Two camera lenses (BGA und CSP)
- Two thermo couple sensors (type K)
- Two PCB magnet holder 40,5mm (standard)
- PCB magnet holder rail 40,5mm
- Two PCB clips to install at hand rest
- Foot switch
- Rework ABC and manual

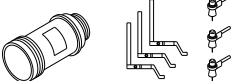

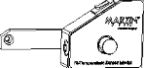
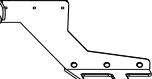




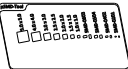

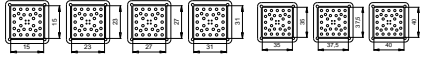
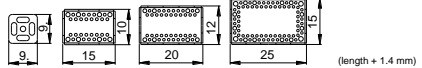
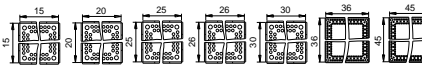
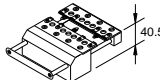

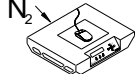
Technical Data

System power consumption:	1000 VA
Power solder pen :	300 W, 35 l/min
Power underheater:	110 W, 2 x IR lamps
Effective heating area:	80 x 60 mm ²
Recommended max. PCB size:	100 x 80 mm ²
Resolution motion system:	0,001 mm
Placement accuracy :	± 0,015 mm (Flip Chip)* ± 0,030 mm (CSP) ± 0,040 mm (BGA)
High resolution CMOS-camera:	5 Mio. Pixel, USB2
Camera field of view (FOV):	14 x 18 mm ² (Flip Chip)* 28 x 37 mm ² (CSP) 37 x 50 mm ² (BGA)
Mains:	1 Phase, 230VAC, Fuse 16A
Pressurized air:	5 - 8 bar, 100 l/min clean dry air
Foot print:	865 x 460 mm ²

* Optional Extras

EXPERT 10.6 IV

Optional Extras

SF66.0004	Micro SMD nozzles and lens for AVP 4 licence MS, 3 n, 3 solder n, lens FC	
DVSX.0007	Report with pcb Identification for ES 05, licence RP	 Report
SF71.0003	IR temperatur sensor for AVP04.1	
SF64.0501	Tool slider for AVP 4.1	
SF64.0525	Dipp tool 32x0,08mm with squeegee for tool slider	
SF64.0526	Dipp tool 32x0,15mm with squeegee for tool slider	
SF64.0527	Dipp tool 32x0,22mm with squeegee for tool slider	
SF64.0520	Print tool with squeegee for tool slider	
SF64.0540	μ SMD tool for tool slider	
SF66.0110	Lens Maxi BGA for AVP4/4XL, f=16mm, 65*85mm	 Maxi-BGA AVP4
LW40.1099	Solder Nozzle Set BGA 7 for all (98%) types of BGA, 7 pieces	
LW01.0400	Soldering Tool Set SO (lead free) for all SO...SOL...TSOP, 4 pieces	 (length + 1.4 mm)
LW01.0100	Soldering Tool Set QFP for all PLCC ...QFP, 7 pieces	
SF03.0019	PCB Clamping Holder 40.5 with 3 fingers for mobile phone pbc on HB-05/ IR/IRD/IRH/IRF/HIF	 40.5
SF71.0001	Side Camera for ES-05, camera, stand, cable, DVD	
DB00.0025	Nitrogen input for DBL 04/05/06 (2.p.r) reduces consumption of N2 for vacuum	 N ₂